

| L Number | Hits    | Search Text   | DB                 | Time stamp       |
|----------|---------|---|--------------------|------------------|
| 1        | 252073  | battery   | USPAT;<br>US-PGPUB | 2004/09/02 07:55 |
| 2        | 1947    | battery and 438/\$.ccls.  | USPAT;<br>US-PGPUB | 2004/09/02 07:55 |
| 3        | 341365  | wiring interconnect   | USPAT;<br>US-PGPUB | 2004/09/02 07:56 |
| 4        | 901     | (battery and 438/\$.ccls.) and (wiring interconnect)  | USPAT;<br>US-PGPUB | 2004/09/02 07:56 |
| 5        | 1584147 | metal\$9  | USPAT;<br>US-PGPUB | 2004/09/02 07:56 |
| 7        | 833     | ((battery and 438/\$.ccls.) and (wiring interconnect)) and metal\$9   | USPAT;<br>US-PGPUB | 2004/09/02 07:57 |
| 8        | 166856  | wafer   | USPAT;<br>US-PGPUB | 2004/09/02 07:57 |
| 9        | 427     | ((battery and 438/\$.ccls.) and (wiring interconnect)) and metal\$9) and wafer  | USPAT;<br>US-PGPUB | 2004/09/02 08:23 |
| 10       | 3701762 | within between  | USPAT;<br>US-PGPUB | 2004/09/02 08:31 |
| 18       | 1       | ("6650000").PN.   | USPAT;<br>US-PGPUB | 2004/09/02 10:09 |
| 19       | 1070    | battery with (wiring interconnect) with (within between)  | USPAT;<br>US-PGPUB | 2004/09/02 10:18 |
| 20       | 853925  | semiconductor integrated  | USPAT;<br>US-PGPUB | 2004/09/02 10:18 |
| 21       | 388     | (battery with (wiring interconnect) with (within between)) and (semiconductor integrated)   | USPAT;<br>US-PGPUB | 2004/09/02 10:19 |
| 22       | 663496  | substrate   | USPAT;<br>US-PGPUB | 2004/09/02 10:19 |
| 23       | 708306  | substrate wafer   | USPAT;<br>US-PGPUB | 2004/09/02 10:19 |
| 25       | 128     | ((battery with (wiring interconnect) with (within between)) and (semiconductor integrated)) and (substrate wafer)   | USPAT;<br>US-PGPUB | 2004/09/02 10:21 |
| 26       | 78      | ((battery with (wiring interconnect) with (within between)) and (semiconductor integrated)) and (substrate wafer)) and @ad<20010116   | USPAT;<br>US-PGPUB | 2004/09/02 10:38 |
| 27       | 11      | ("2800616"   "3536963"   "3558357"   "3634736"   "3648126"   "3656027"   "4014730"   "4737422"   "5437941"   "5455126"   "6123861").PN.   | USPAT              | 2004/09/02 10:35 |
| 28       | 5693    | battery with (wiring interconnect)  | USPAT;<br>US-PGPUB | 2004/09/02 10:38 |
| 29       | 538     | (semiconductor integrated) and substrate and (battery with (wiring interconnect))   | USPAT;<br>US-PGPUB | 2004/09/02 10:38 |
| 30       | 327     | ((semiconductor integrated) and substrate and (battery with (wiring interconnect))) and @ad<20010116  | USPAT;<br>US-PGPUB | 2004/09/02 11:01 |
| 31       | 239     | ((semiconductor integrated) and substrate and (battery with (wiring interconnect))) and @ad<20010116) not (((battery and 438/\$.ccls.) and (wiring interconnect)) and metal\$9) and wafer) not (((battery with (wiring interconnect) with (within between)) and (semiconductor integrated)) and (substrate wafer)) and @ad<20010116)  | USPAT;<br>US-PGPUB | 2004/09/02 11:01 |
| 32       | 4012    | battery with (substrate wafer)  | USPAT;<br>US-PGPUB | 2004/09/02 11:01 |
| 33       | 805     | (wiring interconnect) and (battery with (substrate wafer))  | USPAT;<br>US-PGPUB | 2004/09/02 11:01 |
| 34       | 505     | ((wiring interconnect) and (battery with (substrate wafer))) and @ad<20010116   | USPAT;<br>US-PGPUB | 2004/09/02 11:01 |
| 35       | 347     | ((wiring interconnect) and (battery with (substrate wafer))) and @ad<20010116) not (((semiconductor integrated) and substrate and (battery with (wiring interconnect))) and @ad<20010116) not (((battery and 438/\$.ccls.) and (wiring interconnect)) and metal\$9) and wafer) not (((battery with (wiring interconnect) with (within between)) and (semiconductor integrated)) and (substrate wafer)) and @ad<20010116)) not (((semiconductor integrated) and substrate and (battery with (wiring interconnect))) and @ad<20010116) not (((battery and 438/\$.ccls.) and (wiring interconnect)) and metal\$9) and wafer) not (((battery with (wiring interconnect) with (within between)) and (semiconductor integrated)) and (substrate wafer)) and @ad<20010116) | USPAT;<br>US-PGPUB | 2004/09/02 11:02 |

|    |     |   |                    |                  |
|----|-----|---|--------------------|------------------|
| 36 | 214 | (semiconductor integrated) and (((wiring interconnect) and (battery with (substrate wafer))) and @ad<20010116) not (((semiconductor integrated) and substrate and (battery with (wiring interconnect))) and @ad<20010116) not (((battery and 438/\$.ccls.) and (wiring interconnect)) and metal\$9) and wafer) not (((battery with (wiring interconnect) with (within between)) and (semiconductor integrated)) and (substrate wafer)) and @ad<20010116) not (((semiconductor integrated) and substrate and (battery with (wiring interconnect))) and @ad<20010116) not (((battery and 438/\$.ccls.) and (wiring interconnect)) and metal\$9) and wafer) not (((battery with (wiring interconnect) with (within between)) and (semiconductor integrated)) and (substrate wafer)) and @ad<20010116)) | USPAT;<br>US-PGPUB | 2004/09/02 11:02 |
|----|-----|---|--------------------|------------------|